

FEATURES

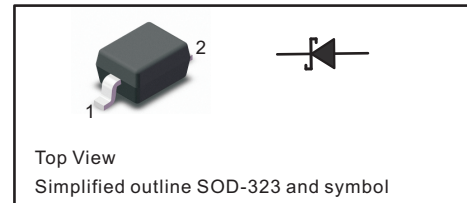
- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SOD-323
- Terminals: Solderable per MIL-STD-750, Method 2026

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

**Absolute Maximum Ratings at 25 °C**

Parameter	Symbols	BAS21H	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	250	V
Maximum RMS voltage	V_{RMS}	200	V
Continuous Forward Current	I_F	250	mA
Repetitive Peak Forward Current	I_{FRM}	625	mA
Non-reptitive Peak Forward Surge Current at 1s at 1ms at 1 us	I_{FSM}	1 3 9	A
Total Power Dissipation	P_{tot}	500	mW
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Characteristics at $T_a = 25\text{ °C}$

Parameter	Symbols	BAS21H	Units
Reverse Breakdown Voltage at $I_R = 100\mu A$	$V_{(BR)R}$	250	V
Maximum Forward Voltage at 100 m A at 200 m A	V_F	1.00 1.25	V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25\text{ °C}$ $T_a = 150\text{ °C}$	I_R	0.1 100	μA
Typical Junction Capacitance at $V_R = 4V$, $f = 1MHz$	C_j	5	pF
Maximum Reverse Recovery Time ⁽¹⁾	t_{rr}	50	ns

(1) Measured with $I_F = 0.5 A$, $I_R = 1 A$, $I_{rr} = 0.25 A$

Fig.1 Forward Current Derating Curve

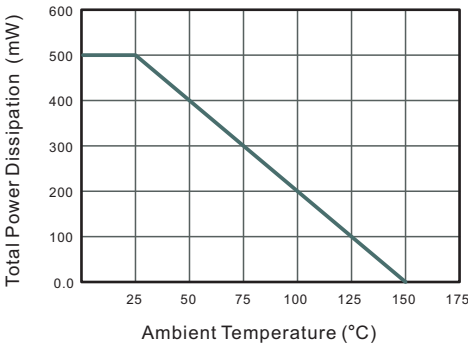


Fig.2 Typical Reverse Characteristics

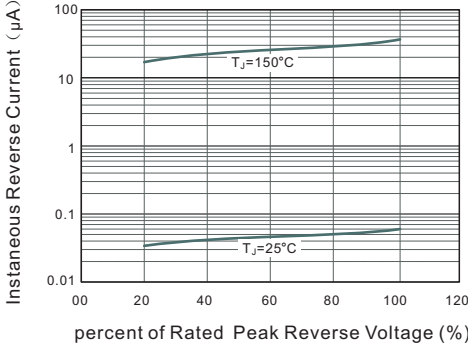


Fig.3 Typical Instaneous Forward Characteristics

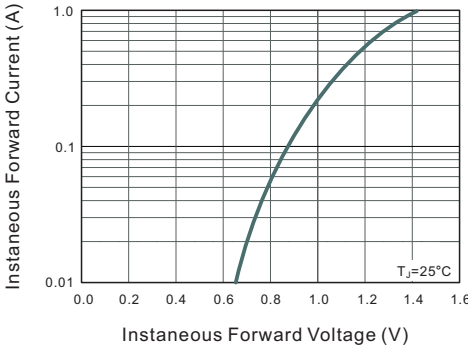
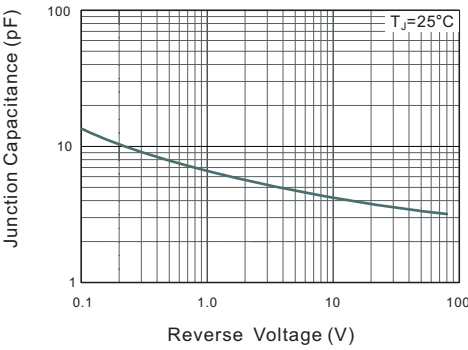


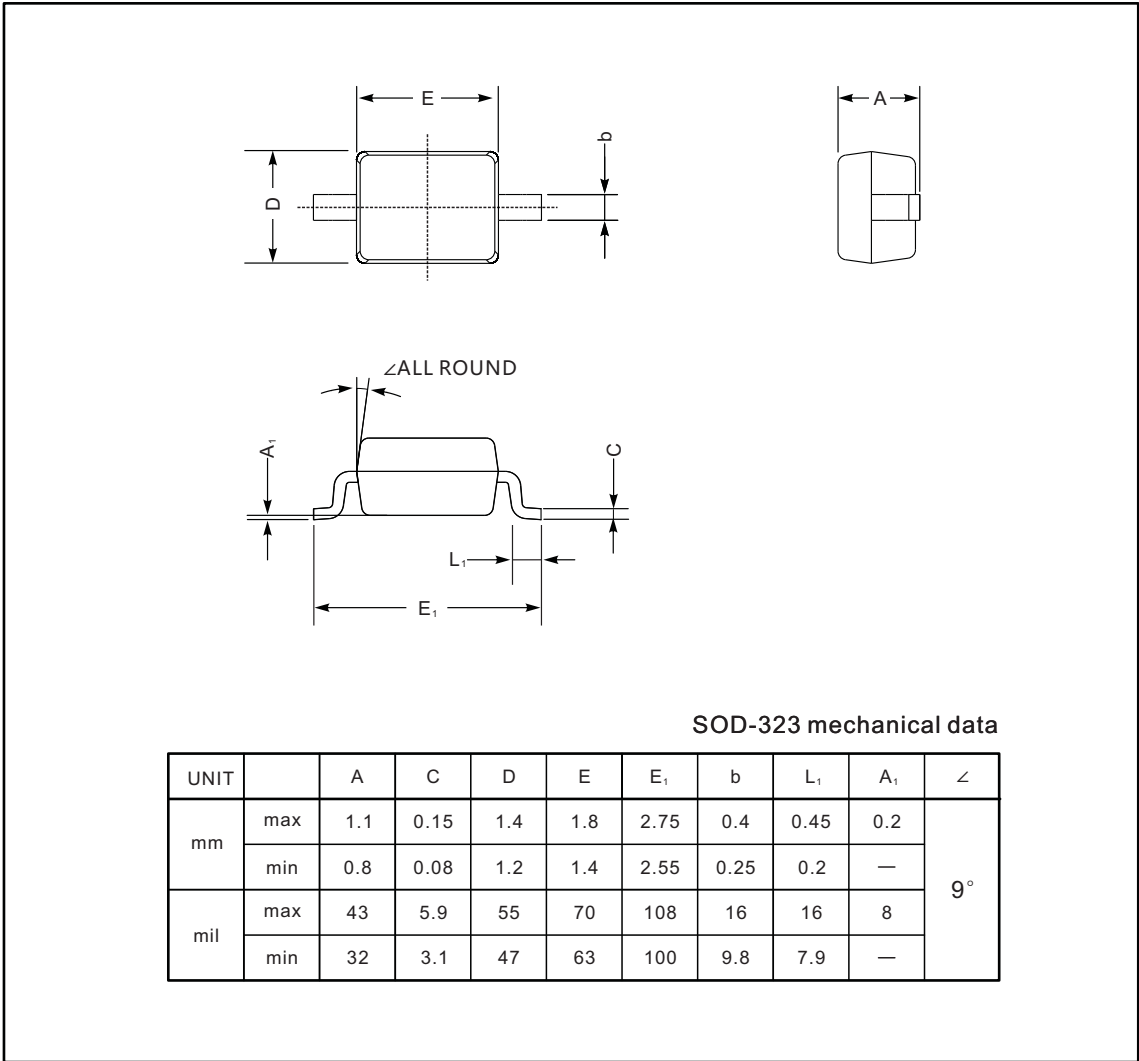
Fig.4 Typical Junction Capacitance



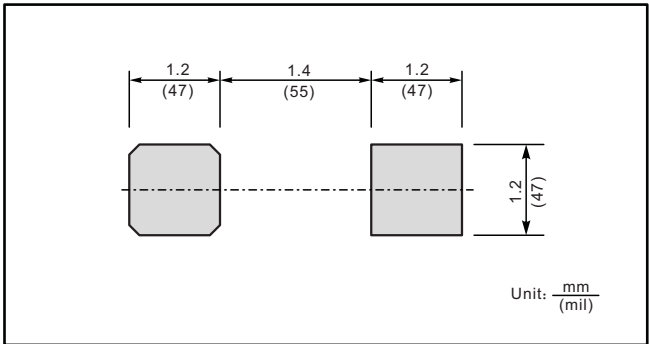
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323



The recommended mounting pad size



Marking

Type number	Marking code
BAV19WS	A8
BAV20WS	T2
BAV21WS	T3